Title (en)

MOLDING COMPOUND.

Title (de)

GIESSMASSE.

Title (fr)

COMPOSE DE MOULAGE.

Publication

EP 0081557 A1 19830622 (EN)

Application

EP 82902032 A 19820517

Priority

US 27302581 A 19810612

Abstract (en)

[origin: WO8204437A1] Molding compounds having improved properties including rapid curing rates and storage stability. These compounds comprise an admixture of: a) from about 5 to 90% by weight of epoxy resin having more than one 1,2-epoxy group per molecule; b) from 0.001 to 5% by weight of metal acetylacetonate having solely metal to oxygen bonds; c) from 0.025 to 30% by weight of phenolic accelerator; and d) from about 10 to 95% by weight of filler, based on the total weight of the composition.

Abstract (fr)

Composes de moulage possedant des proprietes ameliorees comprenant des vitesses elevees de polymerisation ainsi qu'une stabilite au stockage. Ces composes comprennent un melange de: a) d'environ 5 a 90% en poids d'une resine epoxyde possedant plus qu'un groupe 1,2-epoxyde par molecule; b) de 0,001 a 5% en poids d'un acetyle acetonate metallique possedant uniquement des liaisons metal-oxygene; c) de 0,025 a 30% en poids d'un accelerateur phenolique; et d) d'environ 10 a 95% en poids d'un agent de remplissage, par rapport au poids total de la composition.

IPC 1-7

C08L 63/00

IPC 8 full level

C08G 59/62 (2006.01); **C08G 59/00** (2006.01); **C08G 59/40** (2006.01); **C08G 59/68** (2006.01); **C08G 59/70** (2006.01); **C08L 63/00** (2006.01)

CPC (source: EP)

C08G 59/68 (2013.01); **C08G 59/683** (2013.01); **C08G 59/70** (2013.01); **C08L 63/00** (2013.01)

Designated contracting state (EPC)

DE FR GB NL

DOCDB simple family (publication)

WO 8204437 A1 19821223; EP 0081557 A1 19830622; EP 0081557 A4 19831026; JP S58500898 A 19830602

DOCDB simple family (application)

US 8200667 W 19820517; EP 82902032 A 19820517; JP 50202882 A 19820517